PRODUCT SPECIFICATION

CS2004B-D-FSXFSWN-101

V1.0

Feb 23, 2011

Easterntronic LCD Group

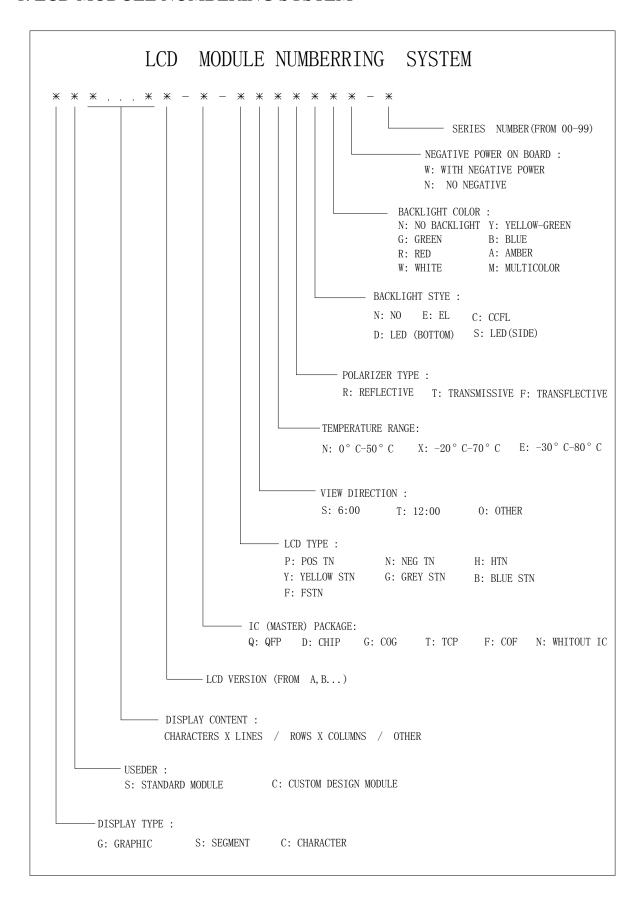
REVISION RECORD

VERSION	DESCRIPTION	DATE
V1.0		Feb 23, 2011

CONTENTS

SECTIONS	DES	SCRIPTION	PAGE NO.	
1. Type Nun	nber and D	escription •••••	• • • • • • • • • • • • • • • • • • • •	4
2. LCD Mod	dule Number	ing System •••	•••••	5
3. Mechanical	Specificatio	ns ·····	•••••	6
4.1 Pin4.2 Ele	s Definition ctrical Block D		•••••	7
5. Absolute	Maximum R	atings ••••••	•••••	8
5.1 Ele	ctrical Maximu	ım Ratings		
5.2 Env	vironmental Co	onditions		
6. Electrical	Specifications	••••••	•••••	9
6.1 Ele	ctrical Charact	eristics		
6.2 Tin	ning Specificat	ion		
7. Power S	Supply for	LCD Module •••	• • • • • • • • • • • • • • • • • • • •	11
8. Electro-O	ptical Chara	cteristic •••••	• • • • • • • • • • • • • • • • • • • •	11
9. Instructio	n Table •••	• • • • • • • • • • • • • • • • • • • •		13
			• • • • • • • • • • • • • • • • • • • •	14
11. Software	examples •	• • • • • • • • • • • • • •	•••••	15
12.Quality un	its	• • • • • • • • • • • • • •	• • • • • • • • • • • • • • • • • • • •	17
13.Character p	pattern •••••	• • • • • • • • • • • • • •	•••••	28
13. Precaution	n for Using	LCM ·····	• • • • • • • • • • • • • • • • • • • •	29
14. Declaratio	n of comformi	ty regarding the lin	nitation of	
dangerou	s substances	• • • • • • • • • • • • • • • • • • • •	• • • • • • • • • • • • • • • • • • • •	30

1. LCD MODULE NUMBERING SYSTEM



4

2. TYPE NUMBER AND DESCRIPTION

Type Number : CS2004B-D-FSXFSWN-101

Description : 20 Characters X 4 lines

LCD Panel : FSTN, Positive, Transflective

Viewing angle : 6H

Duty and Bias : 1/16 duty; 1/5 bias

Logic Voltage : 5.0V

Operating Temperature: -20°C--70°C

Storage Temperature : -30°C--80°C

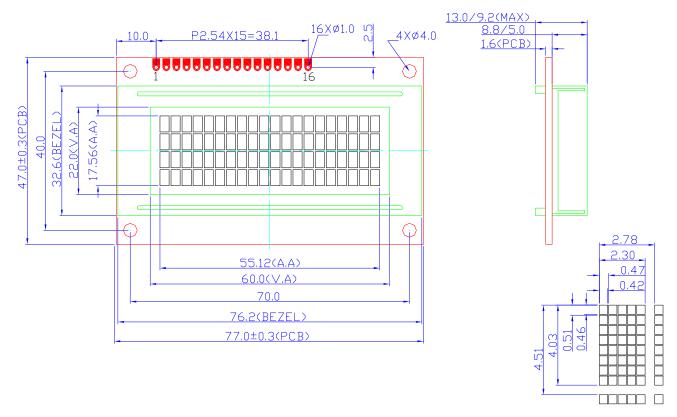
Controller : ST7066U-0B or Equivalent

IC package : Bonding

BackLight Type : Side, white

3. MECHANICAL SPECIFICATIONS:

ITEM	STANDARD VALUE	UNIT			
CHARACTER NUMBER	20 CHARATERS X 4 LINES				
MODULE DIMENSION	77.0 (W) X 47.0 (H) X 13.0 (H)	mm			
DISPLAY AREA	60.0(W) X 22.0 (H)	mm			
CHARACTER FORMAT	5 X 7 DOTS WITH CURSOR				
CHARACTER SIZE	2.3(W) X 4.03(H)	mm			
CHARACTER PITCH	2.78(W) X 4.51(H)	mm			
DOT SIZE	0.42 (W) X 0.46 (H)	mm			
DOT PITCH	0.47 (W) X 0.51 (H)	mm			
APP APPROX WEIGHT	46	g			
LCD TYPE	FSTN, Positive, Transflective				
DUTY AND BIAS	1/16 DUTY ;1/5 BIAS				
VIEWING DIRECTION	6Н				
BACKLIGHT	Side, White				



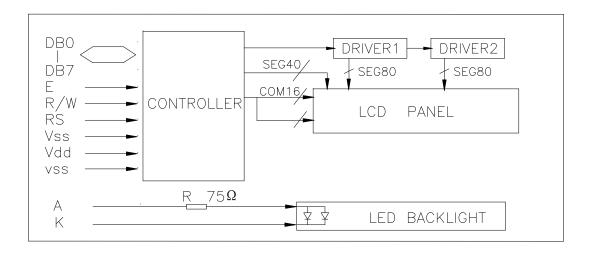
^{*}Non-specificed tolerance is +/-0.2mm

4. ELECTRICAL BLOCK DIAGRAM

4.1 Pin Definition

PIN	SYMBOL	FUNCTION							
1	Vss	Power Supply(GND)							
2	Vdd	Power Supply(+5.0V)							
3	Vo	Contrast Adjust							
4	RS	Instruction/Data Register Select							
5	R/W	Data Bus Line							
6	Е	Enable Signal							
7-14	DB0-DB7	Data Bus Line							
15	A	Power Supply for LED B/L(+)							
16	K	Power Supply for LED B/L(-)							

4.2 Electrical Block Diagram



4.3 Display Character Address Code

DISPLAY POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM	00	01	02	03	04	05	06	07	08	09	0A	0B	00	0D	0E	0F	10	11	12	13
551000	40	41	42	43	44	45	46	47	48	49	4A	4B	40	4D	4E	4F	50	51	52	53
ADDRESS	14	15	16	17	18	19	1A	1B	10	1D	1E	1F	20	21	22	23	24	25	26	27
	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

5. ABSOLUTE MAXIMUM RATINGS

5.1 Electrical Maximum Ratings (Ta=25deg C)

ITEM	SYMBOL	CONDITI ON	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	-	-20	70	deg C
Storage Temp	Ttsg	-	-30	80	deg C

6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5.0V + / - 5%

ITEM	SYMB OL	CONDITIO N	MI N	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vs s	-	-	5.0	-	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 3.3V	4.6	4.8	5.0	V
Input signal voltage	V-ih	"H" level	2.2	1	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	ı	0.6	V
Supply Current (logic)	Icc	1	0.9	1	1.2	mA
Supply Current (LCD)	Io	1	0.15	0.22	0.27	mA
Supply Voltage (LED)	V-bl	1	2.8	3.1	3.3	V
Supply Current (LED)	I-bl	1	-	30	45	mA
*Peak forward current(B/L)	Ifp	I msec pulse 10% Duty Cycle	-	-	120	mA
*Power dissipation(B/L)	Pd		-	-	124	mW

*For operation above 25°C, the If、Ifp&Pd must be derated, the current derating is -0.62 mA/°C for DC drive and -1.72 mA/°C for pulse drive,the power dissipation is -1.92mW/°C. The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.

6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5.0V+/-10%, Vss = 0V 6.2.1Write mode

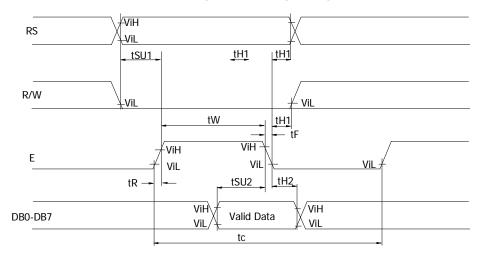
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	40	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

6.2.2 Read mode

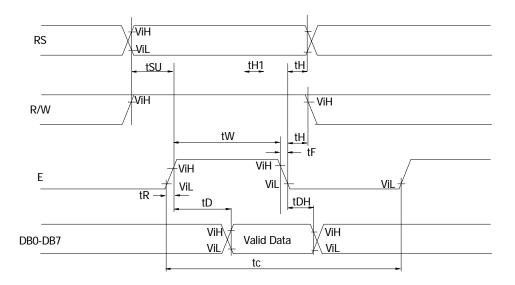
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	10	-	ns

6.2.3 TIMING DIAGRAM

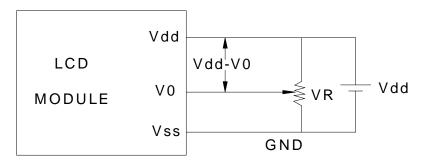
WRITE MODE TIMING DIAGRAM



READ MODE TIMING DIAGRAM



7. POWER SUPPLY FOR LCD MODULE



Vdd - VO: LCD Driving Voltage

VR: 10K - 20K

8. ELECTRO-OPTICAL CHARACTERISTIC

ITEM	SYMB OL	CONDI TION	MIN.	TYP.	MAX.	UNIT	REF.	
Contrast	CR	25℃	-	12	1		Note1	
Rise Time	tr	25℃		160	240	ms	Note2	
Fall Time	tf	25℃	-	100	150	ms	note 2	
Viewing Angle	θ 1- θ 2	25℃			60	DEG	Note 3	
Viewing Angle	Ø1, Ø2	23 C	-40		40	DEG		
Frame	Ff	25℃		64		Hz	noto 2	
Frequency	ΓΊ	23 C		04		ПΖ	note 2	

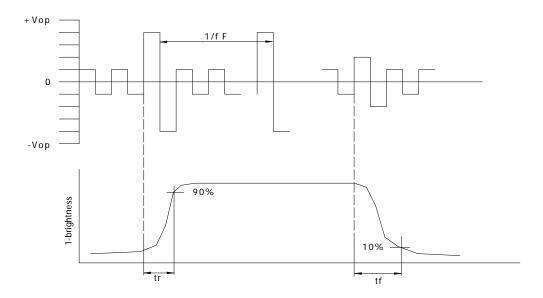
Note(1): Contrast ratio is defined under the following condition:

CR= brightness of non-selected condition

brightness of selected condition

- (a). Temperature----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle---- $\theta = 0$, $\emptyset = 0$
- (d). Operating Voltage---4.8V

Note(2): definition of response time:

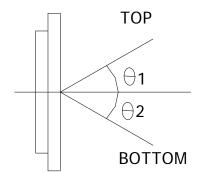


Condition:

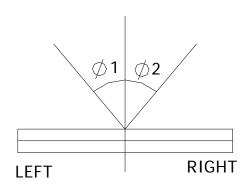
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle---- $\theta = 0$, $\emptyset = 0$
- (d). Operating Voltage---4.8V

Note(3): definition of view angle:

TOP-BOTTOM DIRECTION



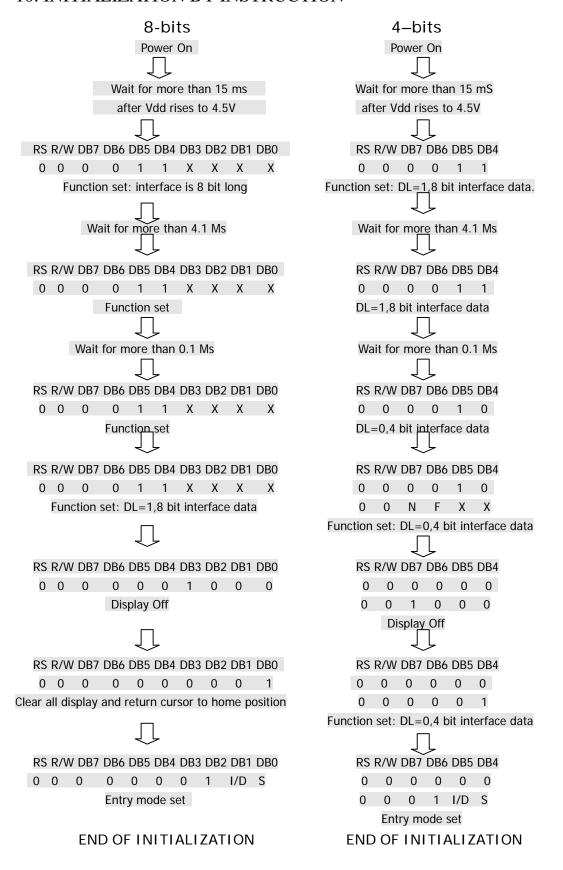
RIGHT-LEFT DIRECTION



9. INSTRUCTION TABLE

Function	R	R	D	D	D	D	D	D	D	D	Description	Execu
							В				•	Time*
							3					(Max)
Clear	0	0									Clears entire display and returns the cursor to	
Display											home position (address 0)	
Return	0	0	0	0	0	0	0	0	1	Χ	Return the cursor to the home position. DD RAM	1.64mS
Home											contents remain unchanged. Set DD RAM address	
											to zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 μ S
mode									/		shift of the display. These operations are	
set									D		performed during data write/read of DD RAM/CG	
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:	
											whole display shift when data is written.	
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 μ S
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.	
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;	
											B=0, Blink OFF.	
Cursor or	0	0	0	0	0	1	S	R	Χ	Χ	Move the cursor and shift the display without	40 μ S
Display							l	/			changing DDRAM contents. S/C=1: Display Shift;	
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;	
											R/L=0:shift to left.	
Function	0	0	0	0	1	D	N	F	Χ	Χ	Set interface data length (DL), number of display	40 μ S
Set						L					lines (N) and character font (F).DL=1: 8 bits;	
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:	
											5X11 dots; F=0: 5X7 dots.	
Set CG	0	0	0	1			A(CG	i		Set CG RAM address. CG RAM data is sent and	40 μ S
RAM add											received after this setting.	
Set DD	0	0	1			Α	D	D			Set DD RAM address. DD RAM data is sent and	40 μ S
RAM Add											received after this setting.	
Read BF	0	1	В				AC	;			Read BUSY FLAG (BF) and the contents of the	0μS
& Addr			F								address counter. BF=1: internal operation; BF=0:	
											can accept instruction.	
Write Data	1	0	١	ΝI	RΙ	TE	<u> </u>	DΑ	T	١	Write data into DD RAM or CG RAM.	40
to RAM										μ S **		
Read Data	1	0		RI	EΑ	νD	D	Α	ГΑ		Read data from DD RAM or CG RAM.	40
from RAM												μ S **

10. INITIALIZATION BY INSTRUCTION



11. SOFTWARE EXAMPLES

8-BIT OPERATION 8 characters X 2 lines

Function	RS RW D7 D6 D5 D4 D3 D2 D1 D0	DISPLAY DESCRIPTION
Power on		Initialization. No display
delay		appears.
Function set	0 0 0 0 1 1 0 0 X X	Sets 8-bit operation, 2-line
		display and 5*7 dots character
		font.
Display OFF	0 0 0 0 0 0 1 0 0 0	Turn off display.
Display ON	0 0 0 0 0 0 1 1 1 0	Turn on display and cursor.
Entry Mode	0 0 0 0 0 0 0 1 1 0	Set mode to increment the
set		address by one and to shift the
		cursor to the right, at the time
		of write to the DD/CG RAM.
		Display is not shifted.
Write data to	1 0 0 1 0 0 1 1 1 1	O Write "O". Cursor incremented
CG/DD RAM		by one and shift to right.
Write data to	1 0 0 1 0 1 0 0 1 0	OR Write "R". Cursor incremented
CG/DD RAM		by one and shift to right
124.11		
Write data to		ORIENT Write "I" "E" "N" "T".
CG/DD RAM		
Set DDRAM	0 0 1 1 0 0 0 0 0	ORIENT Set RAM address so that the
address		
address		cursor is positioned at the head of the Second line
Write data to		
CG/DD RAM		ORIENT Write "D" "S".
CG/DD RAW		<u> </u>
Cursor or	0 0 0 0 0 1 0 0 X X	ORIENT Shift only the cursor position to
display shift		DS the left.
aispiay siliit		the fort.
Write data to		ORIENT Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM		DISPLAY

4-bit operation (4-bits 1 line)

Function RS RW D7 D6 D5 D4 Display Description										
Function	K2	KW	וטו	Dδ	υs	D4	Display	Description		
power on								Initialization. No display appears.		
delay										
Function set	0	0	0	0	1	0		Sets to 4 -bit operation.		
								In this case, operation is handled as 8-bits by		
								initialization, and Only this instruction		
								completes with one write.		
Function set	0	0	0	0	1	0		Sets 4 -bit operation, 1-line display and 5*7		
	0	0	0	0	Χ	Χ		dot character font. (number of display lines and		
								character fonts cannot be changed hence after.)		
Display	0	0	0	0	0	0		Turn on display and cursor.		
ON/OFF	0	0	1	1	1	0	_			
Control										
Entry Mode	0	0	0	0	0	0		Turn on display and cursor.		
Set	0	0	0	1	1	0	_			
Write data to	1	0	0	1	0	0		Write "O". Cursor incremented by one and shift		
CG/DD/ARM	1	0	1	1	1	1		to right.		
						sam	e as 8-bit op	peration		

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

12.2 Scope

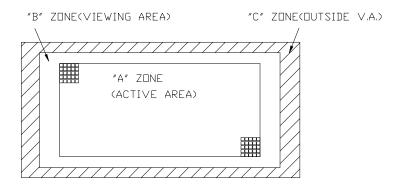
This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

A Zone: Active area. B Zone: Viewing area

C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M): 7~50 pcs LCD screens are cut out of from each 14"×16" mother glass.

Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" mother glass.

12.4 Quality Specification

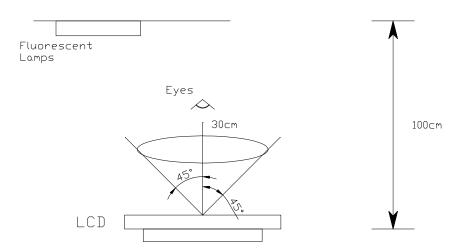
12.4.1 Conditions of Cosmetic Inspection

12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: 65 \pm 20%RH

Ambient Luminance: 40-watt fluorescent lamp.

An appearance test should be conducted by human sight at approximately 30 cm distance from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

V1.0

18

12.4.4 Applicable instrument

- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of	Inspection	on criterion		Drawing
		defects			S	pecification
Major	1.Non-display	Product no	Not	accept		
defect		function				
	2.LCD with	Difference in	Not	accept		
	wrong view	Spec.				
	direction`					
	3.Segment	Part or all pattern	Not	accept		
	missing	do not light up				
	4.Occur high	Current exceed	Not	accept		
	current	designed value				
	5. LC leakage	LC does not	Not	accept		
		fulfill the glass				
		cell				
	6.Deviation	LCM Dimension	According to dimensions			
	from drawing	difference from	noted in the specification			
		drawing and over				
		tolerance				
	7.Wrong type	Wrong polarizer	Not accept			
	applied	attachment				
		Pin attached	Not	accept		
		wrong type				
		applied				
	8.Incorrect	Pin attached	Not	accept		
	pins quality	wrong quantity				
		applied				
Minor	9.Pattern	Segment fatter or	Dimension	Acceptable		→ A ←
defect	deformation	smaller	(mm)	number		
			A≤0.1	Not count		
				(Should not be		
				connected to		
				next dot)		⁷ B

Minor defect	10.Pinholes 11.Blemishes and foreign	Black spot/white spot at activated state Black spot/dust on	1m distance enlarge unde 2. Middle si Diameter(mn	n't be found at e and will not r electronic test ze LCD n) Accept QTY Not count 3 1 0 e LCD n) Accept QTY Not count 2 1 0 dot pattern: f the area of less than or half of one w one defect in ent arest diatance between two is 20mm	$\Phi = (X+Y)/2$
	matters	LCD(non-display	- Large size I Accept if ca	n't find at 1m will not enlarge	$\Phi = (X+Y)/2$

-Middle size LCD
Diameter(mm) Accept QTY $\Phi \leq 0.15 \text{Not count}$
$0.15 < \Phi \le 0.25$ 3
$0.25 < \Phi \le 0.35$
$\Phi > 0.35$ 0
-Small size LCD
Diameter(mm) Accept QTY
$\Phi \le 0.15$ Not count
$0.15 < \Phi \le 0.25$ 2
0.25<Φ≤0.30 1
$\Phi > 0.30$ 0
2.B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
Notcount.
Negative panel:
1. A zone
-Large size LCD
Diameter(mm) Accept QTY
Φ \leq 0.15 Not count
$0.15 < \Phi \le 0.30$ 4
$0.30 < \Phi \le 0.50$
$\Phi > 0.50$ 0
-Middle&small size LCD
Diameter(mm) Accept QTY
Φ≤ 0.15 Not count
$0.15 < \Phi \le 0.25$ 3
$\Phi > 0.25$ 0
2. B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
No count
The nearest diatance allowed
between two black spot is
20mm

12.1	Black	Scratch on glass	Positive panel:	
	es and	•	_	
		or polarizer	1.A zone	₂
scra	atches	surface.And	- Large size LCD	
		foreign linear	Accept if can't find at 1m	
		matters in LCD	distance and will not enlarge	
			under electronic test.	
			-Middle size LCD	
			Diameter(mm) Accept QTY	
			W≤ 0.02 Not count	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.03 < W \le 0.05, L \le 3$ 2	
			0.02< W≤ 0.03,L >4 0	
			$0.03 < W \le 0.05, L > 3 $ 0	
			W>0.05 As the spot criteria.	
			1	
			-Small size LCD	
			Diameter(mm) Accept QTY	
			$W \le 0.02$ Not count	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.02 < W \le 0.05, L \le 2$ 1	
			$0.03 < W \le 0.03, L \le 2$ $0.02 < W \le 0.03, L > 4$ 0	
			,	
			W>0.05 As the spot criteria.	
			2.B zone	
			1.5 times of acceptable largest	
			diameter size of Zone A	
			3.C zone	
			Notcount.	
			Negative panel:	
			1. A zone	
			-Large size LCD	
			Diameter(mm) Accept QTY	
			1	
			$W \le 0.02$ Not count	
			$0.02 < W \le 0.03, L \le 5$ 3	
			$0.03 < W \le 0.05, L \le 4$ 2	
			$0.02 < W \le 0.03, L > 5 $ 0	
			$0.03 < W \le 0.05, L > 4 $ 0	
			W>0.05 As the spot criteria.	
			N. 111	
			-Middle size LCD	

			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 $W > 0.05$ As the spot criteriaSmall size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \ge 3$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05$	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	distance. According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	

Mintor defect	17. Ink printing	17.1 Ink line/pattern	Not acce	pt			
	defect	broken 17.2 Ink pattern/line jagged	Accept if the thick or thin part is less than equal to 25% segment width, or according to the limit specimen				
		17.3 Light leakage	When activated with current white light appears in the position of pinhole or scratch due to ink printing misalignment. According to the pinhole specification.				
		17.4 Ink printing pattern/line uneven	than 1/2V	the thick W. hen W1-V			
Mintor defect	18. Pin defect	18.1 Corrosion or foreign material on terminal legs	Pin incoming defect: oxidized,damage(including pins plating damaged),excess epoxy on bottom glass or terminal legs.Not accept.				`
		18.2 Pin deviation over tolerance	According to the specification				
Mintor defect	19. Chipped glass on	19.1 Chip in lead contact	a	b	С	accept QTY	
	comer	area.	a≤5mm L>5m m	b≤W	c≤T	3	ITO
			a <l L<5m m</l 	b≤W	c≤T	3	T O O
		19.2 Others	Not exc width of	ceed 1/2 seal	c≤T	3	17

3.50	20. 61		T	Τ,	T	Ι .	Τ
Mintor	20. Glass	chip on edge	a	b	С	accept	b A A A A A A A A A A A A A A A A A A A
defect	I			***	<u> </u>	QTY	
	I		a≤5mm	Not	c≤T	3	
	I			exceed			* ************************************
	I			1/2			I
	I			width			
				of seal			
	21. Clipped	21.1Glass chip	a	b	c	accept	ITD
Mintor	electrode pad	on ITO edge				QTY	W
defect	 		a≤4mm	b≤W/4	c≤T	3	
	 		(and				
	 		not				
	l		exceed				~ \
	l		4 ITO				
	l		termina				
	l		1	<u> </u>			
	 	21.2 Glass chip	a	b	c	accept	b b
	 	on ITO back		<u> </u>	<u> </u>	QTY	
	l		a≤5mm	b≤W/3	c≤T	3	1
	l						
	l						W >
3.50		7	1		<u></u>	OTT 7	
Mintor	22.	Extended crack	b		accept	QTY	
defect	Mechanical	inspector shall					W
	damage	attempt to	b≤W/4		2		
	l	remove the chip					
	 	with					b
	 	tweezers,re-eval					
	 	uate if the					
	 	remaining defect					
	l	is still a crack or					
3.6' -4 - "	22 (7)	a chip	NT 4				-1 1
Mintor	2 3. Gla	ass cracks	Not acce	pt			
defect	<u> 1</u>						

Remark:

The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total:

Large size LCD: Zone $A \le 5/unit$, Zone $B \le 5/unit$; Middle size LCD: Zone $A \le 3/unit$, Zone $B \le 3/unit$; Small size LCD: Zone $A \le 2/unit$, Zone $B \le 2/unit$;

12.4.5.2 Other part

The inspection specification as following list:

NO.	Items	Criterion of defects	AQL			
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight. 	Major Minor			
		4. Colour and luminance of backlight should correspond its specification.	Major Major			
2	PCB,COB	1.COB seal may not have pinholes larger than 0.2mm or contamination.				
		2.COB seal surface may not have pinholes through to the IC.	Minor			
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major			
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor			
		5.No oxidation or contamination on PCB connector.	Minor			
		6.Parts on PCB should correspond the characteristic, and not allow wrong parts, missing parts or additional parts.				
		7.The jumper on the PCB should correspond to the characteristic.				
		8.The solder which gets on bezel,LED pad,zebra pad or screw hole pad should be smoothed down.	Major			
		1. No unmelted solder pastes on the PCB.	Minor			
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor			
		3. No short circuits in components on PCB.	Minor			
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor			
		2. No solder residue or solder balls on product.	Minor			
		3. The IC on TCP may not be damaged.	Major			
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor			
		5. Packing method correspond the specification.	Major			
		6. Dimension and structure correspond the specification sheet.	Major			
		7. No dirt and break on the heat seal.	Major			

12.5 Reliability

The LCD module shall not fail the following reliability test.

Item	Condition	Criterion	
High temperature	$+70^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 ho	ours	
operation			
Low temperature	-20°C ±2°C, 8 ho	urs	1.Total current
operation			consumption
Humidity	Operation	$40^{\circ}\text{C} \pm 2^{\circ}\text{C},93\% \pm 2\%\text{RH,8}$	should be below
		hours	double of initial
	Storage	$40 ^{\circ}\text{C} \pm 2 ^{\circ}\text{C},93\% \pm 2\% \text{RH},$	value.
		24 hours	2.Cosmetic defects
High temperature	+80°C ±2°C, 10 h	nours	should not be
storage			happened
Low temperature	-30℃±2℃, 10 h	ours	
storage			
Thermal shock	-20°C∼+70°C		
storage	60min~60min, 5 cy		
Vibration test	Amplitude:0.7~1.0		
	in each direction(X	(X,Y,Z)	
Shock test	To be measured aft		
	80cm high on the c	oncrete surface in packing	
	state.(weight≥15K	Kg,dropping height 60cm;	
	Weight<15Kg,dro	pping height 80cm)	
		Duomino mothod	
		Dropping method corner dropping	
		D A corner: once	
	G	Edge dropping B,C,D edge: once	
	B	F 1 '	
	60/8	80cm Face dropping E,F,G face: once	
	· (Concrete Surface	
	///////////////////////////////////////		

Remark: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

13. character Pattern

NO 7066-0B

<u>NO.7</u>	<u> </u>	<u> </u>														
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	7)															
0111	(8)															
1000	(1)															
1001	(2)															
1010	(3)															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

14. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.
- (3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handing, especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

- (1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

- (3). Only properly grounded soldering irons should be used.
- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- 2.3. Soldering
- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature: 280 $^{\circ}\text{C} \pm 10\,^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- (3). Response time increases with decrease in temperature.
- (4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year from data of shipment. Confirmation of such date shall be based on freight The warranty liability documents. EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above EASTERNTRONIC will not responsible for any subsequent or consequential events.

15. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R. China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2004B-D-FSXFSWN-101 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

- ■Lead
- Mercury
- Cadmium
- Hexavalant chromium
- Polybrominated biphenyls
- Polybrominated diphenylethers

And to the annex which points out the exempted implementations

☐ To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

- Oils containing polychlorinated biphenyl
- Asbestos
- Radioactive substances
 SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 23, 2011

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.